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**From: Charles A. Brill**  
**Texas Instruments Incorporated**  
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Applicant: Mezenner

Art Unit: 2873

Serial No.: 10/749,277

Examiner: Dinh, Jack

Filed: 31 December 2003

Docket No. TI-33824

For: VIA ADHESION IN MULTILAYER MEMS STRUCTURE

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<b>NAME OF INVENTOR(S):</b> Mezenner	
<b>RECEIPT DATE &amp; SERIAL NO.:</b> Application No.: 10/749,277	
<b>TITLE OF INVENTION:</b> VIA ADHESION IN MULTILAYER MEMS STRUCTURE	
<b>Filing Date:</b> 31 December 2003	
<b>TI FILE NO.:</b> TI-33824	<b>DEPOSIT ACCT. NO.:</b> 20-0668
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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Mezenner

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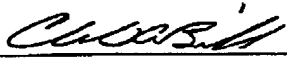
Docket No. TI-33824

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**AMENDMENT**

11 April 2005

Commissioner for Patents  
P.O. Box 1450  
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	11 April 2005
Charles A. Brill	Date

Dear Sir:

In response to the Examiner's Action mailed 10 January 2005, applicant amends as follows:

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